THERMAL INTERFACE APPARATUS, SYSTEMS, AND METHODS

Abstract of the Disclosure

An apparatus and system, as well as fabrication methods therefor, may include a thermal interface material comprised of an array of carbon nanotubes and a buffer layer disposed between the thermal interface material and one of a die or a heat spreader.

"Express Mail" mailing label number: EV332571254US

Date of Deposit: June 30, 2003

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